REVISIONS **APPROVED** DATE LTR DESCRIPTION Delete minimum limits from  $I_{II}$ 16 Mar 1986 and propagation delays. Change  $\mathbf{I}_{\mbox{\scriptsize IL}}$  maximum limit. Editorial changes throughout. Selected item drawing Prepared in accordance with DOD-STD-100 REV PAGE REV STATUS REV PAGES 1 OF PAGES DEFENSE ELECTRONICS SUPPLY CENTER Baker 19Jan. 81 Original Date of BAYTON, BNIO Drawing 19 January 1981 TITLE MICROCIRCUITS, DIGITAL, LOW-POWER SCHOTTKY TTL, BINARY MULTIPLIER, MONOLITHIC SILICON CODE IDENT. NO. DWG NO. 80026 14933 Α PAGE 1 OF 10 REV Α 144 AMSC N/A 5962-E032 DESC FORM DISTRIBUTION STATEMENT A. Approved for public release; distribution is unlimited.

1.	SC	NPF

1.1 <u>Scope</u>. This drawing describes the requirements for monolithic silicon, low-power Schottky TTL, binary multiplier microcircuits. This drawing provides for a level of microcircuit quality and reliability assurance for acquisition of microcircuits in accordance with MIL-M-38510.

1.2 Part number. The complete part number shall be as shown in the following example:







1.2.1 Device type. The device type shall identify the circuit function as follows:

Devi	ce	type

Generic number

Circuit

01

54LS261

2-bit-by-4-bit parallel binary multiplier

1.2.2 <u>Case outlines</u>. The case outlines shall be as designated in appendix C of MIL-M-38510, and as follows:

Outline letter

Case outline

E

D-2 (16-lead, 1/4" x 7/8"), dual-in-line package F-5 (16-lead, 1/4" x 3/8"), flat package

1.3 Absolute maximum ratings.

 -0.5 V dc to +7.0 V dc

-1.5 V dc at -18 mA to +5.5 V dc

Storage temperature range- - - - - - - - - - - - - - - - - Maximum power dissipation per register (PD) 1/-

-65°C to +150°C

Maximum power dissipation per register (rg)

209 mW

Lead temperature (soldering, 10 seconds) - - - -

+300°C

Thermal resistance, junction-to-case ( $\theta_{\text{JC}}$ ) - -

(See MIL-M-38510, appendix C)

Junction temperature  $(T_J)$ - - - - - - - - - -

+175°C

1.4 Recommended operating conditions.

Supply voltage ( $V_{CC}$ ) - - - - - - - - - - - - - Minimum high level input voltage ( $V_{IH}$ ) - - - - - Maximum low level input voltage ( $V_{IL}$ ) - - - - - Case operating temperature range ( $T_C$ ) - - - - -

4.5 V dc minimum to 5.5 V dc maximum

2.0 V dc

0.7 V dc -55°C to +125°C

1/ Must withstand the added PD due to short circuit test (e.g.,  $I_{OS}$ ).

DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO

SIZE				DWG NO			
Α	1	4933			80026		
		REV	A		PAGE	2	



2.1 Government specification and standard. Unless otherwise specified, the following specification and standard, of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

**SPECIFICATION** 

MILITARY

MIL-M-38510 - Microcircuits, General Specification for.

STANDARD

MILITARY

MIL-STD-883

Test Methods and Procedures for Microelectronics.

(Copies of the specification and standard required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

## 3. REQUIREMENTS

- 3.1 Item requirements. The individual item requirements shall be in accordance with MIL-M-38510, and as  $\frac{1}{1}$  Specified herein. The country of manufacture requirement of MIL-M-38510 does not apply.
- 3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.
- 3.2.1 <u>Design documentation</u>. The design documentation shall be in accordance with MIL-M-38510 and, unless otherwise specified in the contract or purchase order, shall be retained by the manufacturer but be available for review by the acquiring activity or contractor upon request.
  - 3.2.2 Terminal connections. The terminal connections shall be as specified on figure 1.
  - 3.2.3 Truth table. The truth table shall be as specified on figure 2.
  - 3.2.4 Case outlines. The case outlines shall be in accordance with 1.2.2.
  - 3.3 Lead material and finish. The lead material and finish shall be in accordance with MIL-M-38510.
- 3.4 Electrical performance characteristics. Unless otherwise specified, the electrical performance characteristics are as specified in table I and apply over the full recommended case operating temperature range.
- 3.5 Marking. Marking shall be in accordance with MIL-M-38510 except the part number shall be in accordance with 1.2 herein. The Vendor Similar Part Number may also be marked in accordance with 6.8 herein. Both part numbers, when used, shall be printed on the same surface. The "M38510/XXX" part number and the "JAN" or "J" mark shall not be used. Lead finish letter "X" is used only as specified in MIL-M-38510 and shall not be marked on the microcircuit or its packaging. The country of origin shall be marked on the microcircuit.
- 3.6 Quality assurance requirements. Microcircuits furnished under this drawing shall have been subjected to, and passed all the requirements, tests, and inspections detailed herein including screening and quality conformance inspections.

DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO	SIZE	14933	DWG NO. 80026
		REV A	PAGE 3

	,

+	ADLE T	Electrical performance characteri	ictics			
l.	ABLE 1.	Electrical performance character	136163.			
Test	  Symbol	Conditions   -55°C < T <sub>C</sub> < +125°C   unless otherwise specified	Group A  subgroups	Limi     Min 	ts Max	Unit
High-level output voltage	I V <sub>OH</sub>	$V_{CC} = 4.5 \text{ V}; I_{OH} = -0.4 \text{ mA}$ $V_{IN} = 0.7 \text{ V or } 2.0 \text{ V}$	1, 2, 3	2.5 		٧
Low-level output voltage	I V <sub>OL</sub>	$V_{CC} = 4.5 \text{ V}, I_{OL} = 4.0 \text{ mA}$ $V_{IN} = 0.7 \text{ V or } 2.0 \text{ V}$	1, 2, 3		0.40	٧
Input clamp voltage	AIC	V <sub>CC</sub> = 4.5 V I <sub>IN</sub> = -18 mA   T <sub>C</sub> = +25°C	1		-1.5	٧
Low-level input current at all inputs; except MO, M1, G	II <sub>IL1</sub>	V <sub>CC</sub> = 5.5 V V <sub>IN</sub> = 0.4 V	1, 2, 3		-400	μ <b>Α</b>
Low-level input current at MO or M1	I IL2	Г     	1, 2, 3		-720	μА
Low-level input current at G	I IL3	T   	1, 2, 3		-600	μА
High-level input current at all inputs except MO or M1	IIH1	V <sub>CC</sub> = 5.5 V V <sub>IN</sub> = 2.7 V	1, 2, 3		20	μА
V V	I IH2	V <sub>CC</sub> = 5.5 V	1, 2, 3	     	100	μА
High-level input current at MO or M1	I I H3	V <sub>CC</sub> = 5.5 V V <sub>IN</sub> = 2.7 V	1, 2, 3	     	40 	μΑ
	I <sub>IH4</sub>	V <sub>CC</sub> = 5.5 V V <sub>IN</sub> = 5.5 V	1, 2, 3	 	200	μА
Short circuit output current	105	V <sub>CC</sub> = 5.5 V V <sub>OUT</sub> = GND <u>1</u> /	1, 2, 3	-15	-100 	mA
Supply current	Icc	V <sub>CC</sub> = 5.5 V V <sub>IN</sub> = GND	1, 2, 3	 	38	l mA

See footnote at end of table.

DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO	SIZE A	14933	DWG NO. 80026
		REV A	PAGE 4

_	٠	
•		•

	т	Conditions		Lin	nits	T
Test	Symbol	$-55^{\circ}C \le T_{C} \le +125^{\circ}C$ unless otherwise specified	Group A    subgroups   	   Min 	Max	⊤ Unit ! 
Propagation delay time from enable	  t <sub>PLH1</sub>	$V_{CC} = 5.0 \text{ V}$ $R_L = 2 \text{ k}\Omega \pm 5\%$ $C_L = 50 \text{ pF} \pm 10\%$	9, 10, 11	İ	52	ns
	t <sub>PHL1</sub>	CL = 50 pF ±10%	9, 10, 11		46	ns
Propagation delay time from any M	tpLH2		9, 10, 11		58	ns
	tpHL2		9, 10, 11	   	52	ns
Propagation delay time from any B	t <sub>PLH3</sub>	•	9, 10, 11		61	ns
	tpHL3	•	9, 10, 11	1	55	l l ns

<sup>1/</sup> Not more than one output should be shorted at one time, and the duration of the short circuit condition should not exceed one second.

DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO

SIZE CODE IDENT. NO. DWG NO. 80026

REV A PAGE 5

Powered by ICminer.com Electronic-Library Service CopyRight 2003

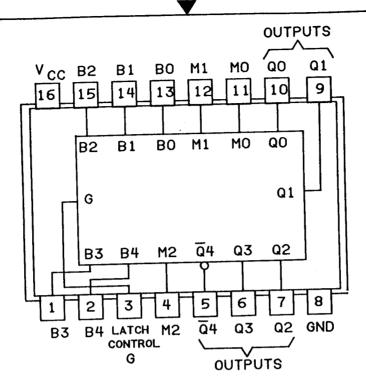


FIGURE 1. Terminal connections.

T Inp	outs		T	0u	tputs		
Latch	Muli	tiplier		0.0	00	01	QO I
control	M2   N	MO IN	7 04	Q3 	Q2	Q1	<del></del>
L	L	X X L L H H L H L H H H H H H H H H H H	Q4 <sub>0</sub>	Q3 <sub>0</sub> B4 B4 B3 B3 B4 B4	Q2 <sub>0</sub> B3 B3 B2 B2 B3 B3	Q1 <sub>0</sub> B2 B2 B1 B1 B2 B2	QOO   B1   B0   B1   B1   B1   B1   B1   B1

H = high level, L = low level, X = irrelevant.  $\overline{Q}40...Q0_0$  = The logic level of the same output before the high-to-low transition of G. B4...B0 = The logic level of the indicated multiplicand (B) input.

FIGURE 2. Truth table.

DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO	SIZE A	14933	NO. DWG NO	80026	
		REV	А	PAGE	6
DESC FORM 144A	<u> </u>	<b>A</b>			

**APR 83** 

- 3.6.1 Screening. Screening shall be in accordance with method 5004, class B, of MIL-STD-883 and 4.2 herein.
- 3.6.2 Qualification. Qualification inspection for the device type specified herein shall not be required.
- 3.6.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with MIL-M-385 $\overline{10}$  and 4.4 herein.
- 3.6.4 Burn-in test circuit documentation. The burn-in test circuit documentation shall be made available to the acquiring activity upon request.
- 3.7 Manufacturer eligibility. To be eligible to supply microcircuits to this drawing, a manufacturer shall have manufacturer certification in accordance with MIL-M-38510 for at least one line and have part I listing on Qualified Products List QPL-38510 for at least one device type (not necessarily the one for which the acquisition of this drawing is to apply).
- 3.8 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply (see 6.7 and 6.8).
  - 4. QUALITY ASSURANCE PROVISIONS
- 4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with MIL-M-38510 and method 5005 of MIL-STD-883, except as modified herein.
- 4.2 Screening. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:
  - a. Burn-in test (method 1015 of MIL-STD-883).
    - (1) Test condition A, B, C, or D.
    - (2)  $T_A = +125^{\circ}C$ , minimum.
  - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.
  - c. The percent defective allowable (PDA) shall be as specified in MIL-M-38510.
- 4.3 Qualification inspection. Qualification inspection for the device type specified herein shall not be required.
- 4.4 Quality conformance inspection. Quality conformance inspection shall be in accordance with MIL-M-38510 and method 5005 of MIL-STD-883. Groups A and B inspections shall be performed on each inspection lot or as specified in method 5005 of MIL-STD-883. Groups C and D shall be performed on a periodic basis in accordance with MIL-M-38510. Generic test data (see 6.5) may be used to satisfy the requirements for groups C and D inspections. Manufacturers shall keep lot records for 5 years (minimum), monitor for compliance to the prescribed procedures, and observe that satisfactory manufacturing conditions and records on lots are maintained for these devices. The records, including an attributes summary of all screening and quality conformance inspections conducted on each lot, shall be available for review by customers at all times.

DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO	SIZE A	14933	D <b>W</b> G NO. 80026	
		REV A	PAGE	7

## TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (per method 1 5005, table I)
Interim electrical parameters  (method 5004)	
Final electrical test parameters  (method 5004)	1*, 2, 3, 9
Group A test requirements   (method 5005)	1, 2, 3, 7, 9
Groups C and D end-point  electrical parameters  (method 5005)	1, 2, 3
Additional electrical subgroups  for group C periodic inspections	10, 11**

- \* PDA applies to subgroup 1 (see 4.2c).
   \*\* Subgroups 10 and 11, if not tested, shall be guaranteed to the specified limits in table I.
- 4.4.1 Group A inspection. Group A inspection shall consist of the test subgroups and LTPD values shown in table I of method 5005 of MIL-STD-883, class B, and as follows:
  - a. Tests shall be as specified in table II herein.
  - b. Subgroups 4, 5, 6, and 8 of table I of method 5005 of MIL-STD-883 shall be omitted.
  - c. Subgroup 7 tests shall verify the truth table.
- 4.4.2 Group B inspection. Group B inspection shall consist of the test subgroups and LTPD values shown in table IIb of method 5005 of MIL-STD-883, class B.
- 4.4.3 Groups C and D inspections. Groups C and D inspections shall consist of the test subgroups and LTPD values shown in tables III and IV of method 5005 of MIL-STD-883, class B, and as follows:
  - a. End-point electrical parameters shall be as specified in table II herein.
  - b. Steady-state life test (method 1005 of MIL-STD-883) conditions:
    - (1) Test condition A, B, C, or D.
    - (2)  $T_A = +125^{\circ}C$ , minimum.
    - (3) Test duration: 1,000 hours, except as permitted by appendix B of MIL-M-38510 and method 1005 of MIL-STD-883.

DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO	SIZE A	14933	DWG NO. 80026	·
		REV A	PAGE	8



- 5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.
- 6. NOTES
- 6.1 Notes. Only the note "Reevaluation of lot quality" of the notes specified in MIL-M-38510 shall apply to this drawing.
- 6.2 Intended use. Microcircuits conforming to this drawing are intended for use when military specifications do not exist and qualified military devices that will perform the required function are not available for OEM application. This drawing is intended exclusively to prevent the proliferation of unnecessary duplicate specifications, drawings, and stock catalog listings. When a military specification exists and the product covered by this drawing has been qualified for listing on QPL-38510, this drawing will be inactivated and will not be used for new design. The QPL-38510 product shall be the preferred item for all applications.
  - 6.3 Ordering data. The contract or purchase order should specify the following:
    - a. Complete part number (see 1.2).
    - Requirements for delivery of one copy of the quality conformance inspection data pertinent to the device inspection lot to be supplied with each shipment by the device manufacturer, if applicable.
    - c. Requirements for certificate of compliance, if applicable.
    - Requirements for notification of change of product or process to contracting activity, if applicable.
    - e. Requirements for special carriers, lead lengths, or lead forming, if applicable. These requirements shall not affect the part number. Unless otherwise specified, these requirements will not apply to direct shipment to the Government.
  - 6.4 Replaceability. Replaceability is determined as follows:
    - a. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
    - b. When a QPL source is established, the part numbered device specified in this drawing will be replaced by the microcircuit identified as part number M38510/31801B---
- 6.5 Generic test data. Generic test data may be used to satisfy the requirements of 4.4.3. Group C generic test data shall be on date codes no more than 1 year old and on a die in the same microcircuit group (see appendix E of MIL-M-38510) with the same material, design and process and from the same plant as the die represented. Group D generic data shall be on date codes no more than 1 year old and on the same package type (terms, definitions, and symbols of MIL-M-38510) and from the same plant as the package represented. The vendor is required to retain the generic data for a period of not less than 5 years from the date of shipment.
- 6.6 Comments. Comments on this drawing should be directed to DESC-ECS, Dayton, OH 45444, or telephone (513)296-5375.
- 6.7 Submission of certificate of compliance. The certificate of compliance submitted to DESC-ECS, prior to listing as an approved source of supply in 6.8, shall state the manufacturer's product meets the requirements herein.

DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO	SIZE	14933		DWG NO. 80026	
			REV A		PAGE 9

6.8 Approved source of supply. An approved source of supply is listed herein. Additional sources will be added as they become available. The vendor listed herein has agreed to this drawing and a certificate of compliance (see 3.8) has been submitted to DESC-ECS.

DESC drawing   part number	Vendor   FSCM   number	Vendor similar part number 1/	Replacement  military specification    part number
8002601EX	01295	SNJ54LS261J	M38510/31801BEX
8002601FX	01295	SNJ54LS261W	M38510/31801BFX

 $\frac{1}{a}$  Caution. Do not use this number for item acquisition. Items  $\frac{1}{a}$  Cautied to this number may not satisfy the performance requirements of this drawing.

Vendor FSCM number 01295 Vendor name and address

Texas Instruments, Inc. P.O. Box 6448 Midland, TX 79701

DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO

SIZE CODE IDENT. NO. DWG NO.

80026

REV A PAGE 10

DESC FORM 144A APR 83

014930 \_ \_ \_